



Docket No.: 43890-439

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of :
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Noboru MOHRI, et al. :
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Serial No.: :
(Divisional of Serial No. 09/041,666) : Group Art Unit:
:

Filed: September 14, 2000 : Examiner:
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For: **PACKAGING SUBSTRATE AND METHOD OF MANUFACTURING THE SAME**

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PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

Prior to examination of the above-referenced application, please amend the application as follows:

IN THE SPECIFICATION:

Page 26, line 14, after "7.2 x 10⁻⁶/C.", please insert --It is noted that the first insulating layer 6 and the second insulating layer 16 have a thermal expansion coefficient +/- 10% of the thermal expansion coefficient of the circuit substrate. In addition, the first insulating layer 6 and the second insulating layer 16 can be formed simultaneously.--

IN THE CLAIMS:

Please amend claim 22 as follows:

22. (Amended) A packaging substrate comprising:

a circuit substrate,

a first conductor pattern formed by an intaglio printing means based on flexible resin base

material and transferred onto said circuit substrate,

a second conductor pattern electrically connected to said first conductor pattern on the opposite side of the circuit substrate via through holes, and

a first ball-shaped solder joined to said second conductor pattern,

wherein a surface roughness of the circuit substrate is made larger on a printing surface of the second conductor pattern than on a printing surface of the first conductor pattern.

REMARKS

Entry of this preliminary amendment is respectfully requested.

Respectfully submitted,

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